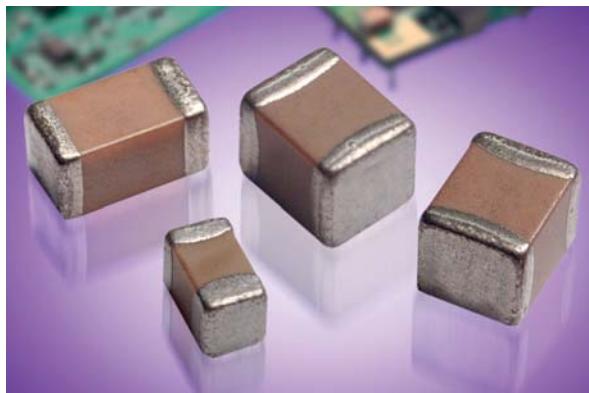


X7S Dielectric

General Specifications



GENERAL DESCRIPTION

X7S formulations are called "temperature stable" ceramics and fall into EIA Class II materials. Its temperature variation of capacitance is within $\pm 22\%$ from -55°C to $+125^{\circ}\text{C}$. This capacitance change is non-linear.

Capacitance for X7S varies under the influence of electrical operating conditions such as voltage and frequency.

X7S dielectric chip usage covers the broad spectrum of industrial applications where known changes in capacitance due to applied voltages are acceptable.

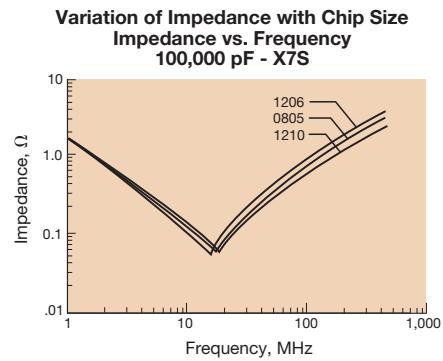
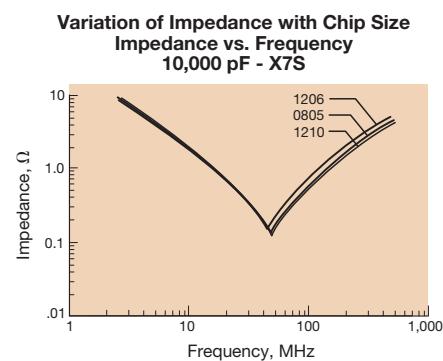
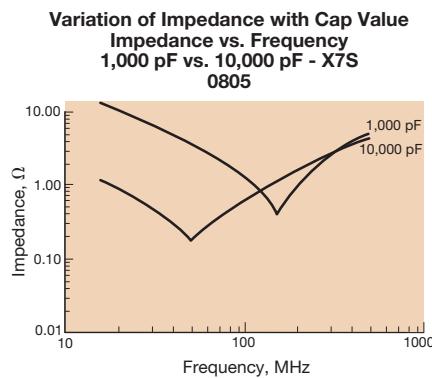
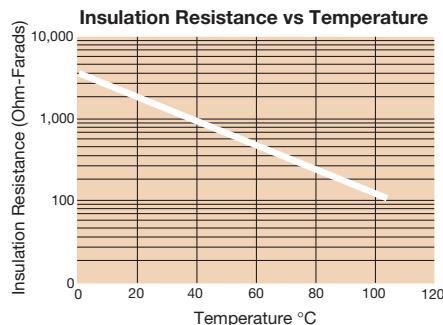
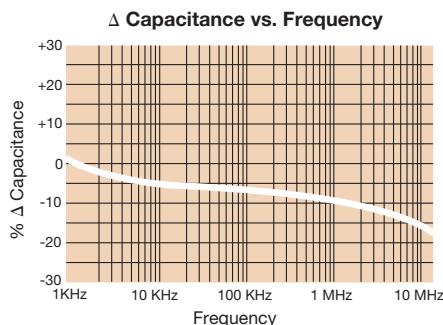
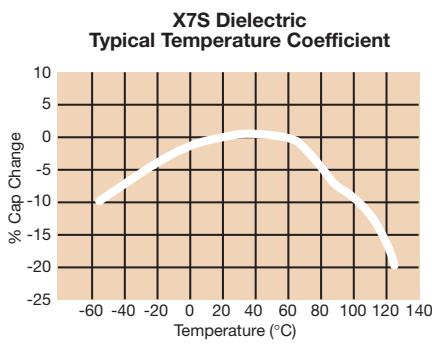
PART NUMBER (see page 2 for complete part number explanation)

1206	Z	Z	105	M	A	T	2	A
Size (L" x W")	Voltage 4 = 4V 6 = 6.3V Z = 10V Y = 16V 3 = 25V 5 = 50V 1 = 100V 2 = 200V	Dielectric Z = X7S	Capacitance Code (in pF) 2 Sig. Digits + Number of Zeros	Capacitance Tolerance K = $\pm 10\%$ M = $\pm 20\%$	Failure Rate A = N/A	Terminations T = Plated Ni and Sn	Packaging 2 = 7" Reel 4 = 13" Reel	Special Code A = Std. Product



NOTE: Contact factory for availability of Tolerance Options for Specific Part Numbers.

TYPICAL ELECTRICAL CHARACTERISTICS



X7S Dielectric



Specifications and Test Methods

Parameter/Test	X7S Specification Limits		Measuring Conditions	
Operating Temperature Range	-55°C to +125°C		Temperature Cycle Chamber	
Capacitance	Within specified tolerance			
Dissipation Factor	≤ 5.0% for ≥ 100V DC rating ≤ 5.0% for ≥ 25V DC rating ≤ 10.0% for ≥ 10V DC rating ≤ 10.0% for ≤ 10V DC rating		Freq.: 1.0 kHz ± 10% Voltage: 1.0Vrms ± .2V For Cap > 10 µF, 0.5Vrms @ 120Hz	
Insulation Resistance	100,000MΩ or 1000MΩ - µF, whichever is less		Charge device with rated voltage for 120 ± 5 secs @ room temp/humidity	
Dielectric Strength	No breakdown or visual defects		Charge device with 300% of rated voltage for 1-5 seconds, w/charge and discharge current limited to 50 mA (max)	
Resistance to Flexure Stresses	Appearance	No defects		
	Capacitance Variation	≤ ±12%		
	Dissipation Factor	Meets Initial Values (As Above)		
	Insulation Resistance	≥ Initial Value x 0.3		
Solderability	≥ 95% of each terminal should be covered with fresh solder		Dip device in eutectic solder at 230 ± 5°C for 5.0 ± 0.5 seconds	
Resistance to Solder Heat	Appearance	No defects, <25% leaching of either end terminal		
	Capacitance Variation	≤ ± 7.5%		
	Dissipation Factor	Meets Initial Values (As Above)		
	Insulation Resistance	Meets Initial Values (As Above)		
	Dielectric Strength	Meets Initial Values (As Above)		
Thermal Shock	Appearance	No visual defects	Step 1: -55°C ± 2° 30 ± 3 minutes	
	Capacitance Variation	≤ ± 7.5%	Step 2: Room Temp ≤ 3 minutes	
	Dissipation Factor	Meets Initial Values (As Above)	Step 3: +125°C ± 2° 30 ± 3 minutes	
	Insulation Resistance	Meets Initial Values (As Above)	Step 4: Room Temp ≤ 3 minutes	
	Dielectric Strength	Meets Initial Values (As Above)	Repeat for 5 cycles and measure after 24 ± 2 hours at room temperature	
Load Life	Appearance	No visual defects	Charge device with 1.5 rated voltage (≤ 10V) in test chamber set at 125°C ± 2°C for 1000 hours (+48, -0) Remove from test chamber and stabilize at room temperature for 24 ± 2 hours before measuring.	
	Capacitance Variation	≤ ±12.5%		
	Dissipation Factor	≤ Initial Value x 2.0 (See Above)		
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)		
	Dielectric Strength	Meets Initial Values (As Above)		
Load Humidity	Appearance	No visual defects	Store in a test chamber set at 85°C ± 2°C/ 85% ± 5% relative humidity for 1000 hours (+48, -0) with rated voltage applied. Remove from chamber and stabilize at room temperature and humidity for 24 ± 2 hours before measuring.	
	Capacitance Variation	≤ ±12.5%		
	Dissipation Factor	≤ Initial Value x 2.0 (See Above)		
	Insulation Resistance	≥ Initial Value x 0.3 (See Above)		
	Dielectric Strength	Meets Initial Values (As Above)		

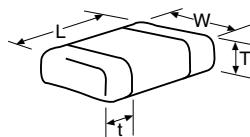
X7S Dielectric



Capacitance Range

PREFERRED SIZES ARE SHADED

SIZE	0402	0603	0805	1206	1210
Soldering	Reflow/Wave	Reflow/Wave	Reflow/Wave	Reflow/Wave	Reflow Only
Packaging	All Paper	All Paper	Paper/Embossed	Paper/Embossed	Paper/Embossed
(L) Length mm (in.)	1.00 ± 0.10 (0.040 ± 0.004)	1.60 ± 0.15 (0.063 ± 0.006)	2.01 ± 0.20 (0.079 ± 0.008)	3.20 ± 0.20 (0.126 ± 0.008)	3.20 ± 0.20 (0.126 ± 0.008)
(W) Width mm (in.)	0.50 ± 0.10 (0.020 ± 0.004)	0.81 ± 0.15 (0.032 ± 0.006)	1.25 ± 0.20 (0.049 ± 0.008)	1.60 ± 0.20 (0.063 ± 0.008)	2.50 ± 0.20 (0.098 ± 0.008)
(t) Terminal mm (in.)	0.25 ± 0.15 (0.010 ± 0.006)	0.35 ± 0.15 (0.014 ± 0.006)	0.50 ± 0.25 (0.020 ± 0.010)	0.50 ± 0.25 (0.020 ± 0.010)	0.50 ± 0.25 (0.020 ± 0.010)
WWDC	6.3	6.3	4	10 50 100	6.3
Cap (pF)	100 150 220				
	330 470 680				
	1000 1500 2200				
	3300 4700 6800				
Cap (μF)	0.010 0.015 0.022				
	0.033 0.047 0.068	C			
	0.10 0.15 0.22	C			
	0.33 0.47 0.68	G G G			
	1.0 1.5 2.2	G	N N		
	3.3 4.7 10		N Q	Q*	
	22 47 100				Z
WWDC	6.3	6.3	4	10 50 100	6.3
SIZE	0402	0603	0805	1206	1210



Letter	A	C	E	G	J	K	M	N	P	Q	X	Y	Z
Max. Thickness	0.33 (0.013)	0.56 (0.022)	0.71 (0.028)	0.90 (0.035)	0.94 (0.037)	1.02 (0.040)	1.27 (0.050)	1.40 (0.055)	1.52 (0.060)	1.90 (0.075)	2.29 (0.090)	2.54 (0.100)	2.79 (0.110)
PAPER					EMBOSSED								

*Contact Factory for Specifications